

RX Family

List of Firmware Integration Technology modules included with RX Driver Package

Introduction

This application note indicates Firmware Integration Technology (FIT) module version included with RX Driver Package (RDP).

Target Device

RX Family MCU corresponding to FIT module.

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1. Overview

Indicates FIT module version included with RDP.

2. List of FIT modules included with RX Driver Package

List of FIT modules included with RDP in the table below.

Table 2.1 List of device driver included with RDP

Table with columns: FIT Module, Document Number, and RDP (1.10 to 1.34). Rows include modules like BSP, LVD, LPC, VBATT, IRQ, DTC, DMAC, GPIO, MPC, CMT, CMTW, RTC, LPT, IWDT, WDT, SCI, RSCI, SCIFA, SCI-IIC, RIIC, RIICHS, RSPI, RSPIA, QSPI, QSPIX, USB Basic, USB Basic Mini, USB HMSC, USB HMSC Mini, USB HCD, USB HCD Mini, USB HHID, USB HHID Mini, USB PMSC, USB PMSC Mini, USB PCDC, USB PCDC Mini, USB PHID, USB PHID Mini, EPTC, EPTC Light, ETHERC, CAN, RSCAN, IrDA, PDC, SDHI, SDI, MMCIF, DSMIF, S12AD, DAC, Flash, SRC, SSI, TSIP, LCDC, GLCDC, Unique ID, BYTEQ, LONGQ.

FIT Module	Document Number	RDP																						
		1.10	1.11	1.12	1.13	1.14	1.15	1.16	1.17	1.18	1.19	1.20	1.22	1.23	1.24	1.25	1.26	1.27	1.28	1.30	1.31	1.32	1.33	1.34
QE CTSU	R01AN4469	-	-	-	-	-	-	-	1.00	1.00	1.00	1.00	1.00	1.00	1.10	1.10	1.11	1.11	1.11	1.11	2.00	2.00	2.01	2.10
ELC	R01AN3066	-	1.10	1.10	1.20	1.20	1.20	1.20	1.20	1.20	1.21	1.21	1.21	1.21	1.21	1.21	2.00	2.00	2.00	2.00	2.00	2.01	2.01	2.01
DRW2D	R01AN5373	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.10	1.10	1.10	1.11	1.11	1.11	1.11	

Table 2.2 List of middleware included with RDP

FIT Module	Document number	RDP																							
		1.10	1.11	1.12	1.13	1.14	1.15	1.16	1.17	1.18	1.19	1.20	1.22	1.23	1.24	1.25	1.26	1.27	1.29	1.30	1.31	1.32	1.33	1.34	
TCP/IP for Embedded system M3S-T4-Tiny Module	R20AN0051	2.05	2.05	2.06	2.06	2.07	2.07	2.07	2.08	2.08	2.08	2.08	2.09	2.09	2.09	2.09	2.09	2.09	2.09	2.10	2.10	2.10	2.10	2.10	
Interface conversion module for Ethernet Driver and Embedded system M3S-T4-Tiny	R20AN0311	1.04	1.05	1.06	1.06	1.06	1.06	1.07	1.07	1.07	1.07	1.07	1.08	1.08	1.08	1.08	1.08	1.08	1.08	1.09	1.09	1.09	1.09	1.09	
Embedded TCP/IP M3S-T4-Tiny Socket API Module	R20AN0296	1.30	1.31	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
System Timer Module	R20AN0431	-	-	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	
SX-ULPGN-2000 Wi-Fi Module Control Module	R01AN4664	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.13	1.14	
BLE Module (BLE)	R01AN4860	-	-	-	-	-	-	-	-	-	-	-	1.01	1.01	1.10	1.10	2.00	2.10	2.11	2.20	2.20	2.30	2.30	-	
RYZ012 Bluetooth Low Energy Module	R01AN6290	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.01	
QE Utility Module (Profiles)	R01AN4907	-	-	-	-	-	-	-	-	-	-	-	0.90	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.10	1.10		
Mesh Module (Mesh)	R01AN4930	-	-	-	-	-	-	-	-	-	-	-	1.00	1.01	1.01	1.01	1.10	1.10	1.10	1.10	1.10	1.20	1.20		
RYZ014A Cellular Module	R01AN6324	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.04		
SD memory card driver module	R01AN4233	-	-	-	-	-	-	2.02	2.03	2.03	2.03	2.03	2.03	2.03	2.03	2.03	3.00	3.00	3.00	3.00	3.00	3.00	3.00	3.00	
Flash Memory Data Management Module	R20AN0507	-	-	-	-	-	-	-	-	-	-	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	2.01	
Clock Synchronous Control Module for Serial Flash Memory Access	R01AN2662	2.33	2.33	2.33	2.34	2.34	2.34	2.34	2.34	2.34	3.00	3.01	3.01	3.01	3.01	3.01	3.01	3.01	3.01	3.02	3.02	3.02	3.03	3.03	
Clock Synchronous Control Module for EEPROM Access	R01AN2325	2.33	2.33	2.33	2.34	2.34	2.34	2.34	2.34	2.34	3.00	3.01	3.01	3.01	3.01	3.01	3.01	3.01	3.01	3.02	3.02	3.02	3.02	3.02	
Memory Access Driver Interface Module	R01AN4548	-	-	-	-	-	-	-	-	-	1.00	1.01	1.01	1.01	1.02	1.02	1.02	1.03	1.03	1.03	1.03	1.03	1.04	1.04	
JPEG Decoder Module	R20AN0104	-	-	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	2.06	
JPEG Encoder Module	R20AN0263	-	-	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	1.01	
Sound Playback/Compression System (Original ADPCM Codec) [M3S-S2-Tiny] Module	R20AN0037	3.03	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	
Open Source FAT File System [M3S-TFAT-Tiny] Module	R20AN0038	3.02	3.03	3.03	3.03	3.03	3.03	3.03	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	3.04	4.00	4.01	4.01	4.02	4.02	4.02	4.02	
M3S-TFAT-Tiny Memory Driver Interface Module	R20AN0335	1.02	1.03	1.03	1.03	1.03	1.03	1.04	1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05	2.00	2.10	2.10	2.20	2.20	2.20	2.20	
Firmware Update Module	R01AN5824	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.01	1.01	1.01	1.02	1.03	
Sensor Communication Middleware Control Module	R01AN5895	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.00	1.00	1.20	1.21	
HS300x Sensor Control Module	R01AN5893	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.00	1.10	1.11	1.22	
FS2012 Sensor Control Module	R01AN6045	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.01	1.02	
ZMOD4410 and ZMOD4510 Sensor Control Module	R01AN6046	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.10	1.20	
QE Touch Module	R01AN4470	-	-	-	-	-	-	1.00	1.00	1.00	1.00	1.00	1.00	1.10	1.10	1.11	1.11	1.11	1.11	1.11	2.00	2.00	2.01	2.10	
Aeropoint module	R01AN5793	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.00	1.00	1.00	1.00	
emWin v.6.14 module	R01AN5533	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.10	1.10	1.30	1.30	1.30	-	-	
emWin v.6.22 module	R01AN5983	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1.00	1.00	

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Aug. 31. 2021	—	First edition issued
1.01	Apr. 13. 2022	3-4	Table 1.2 Deleted v1.21 and added V1.33 and V1.34. Modified content.
		5-6	Table 2.2 Deleted v1.21 and added V1.33 and V1.34. Modified content.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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